

7-104355-0 ✓ ACTIVE

[AMPMODU](#) | [AMPMODU Headers](#)

TE Internal #: 7-104355-0

AMPMODU Headers, PCB Mount Header, Right Angle, Board-to-Board, 80 Position, 2.54mm [.1in] Centerline, Breakaway, Tin, Printed Circuit Board

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PCB Connector Assembly Type: **PCB Mount Header**

PCB Mount Orientation: **Right Angle**

Connector System: **Board-to-Board**

Number of Positions: **80**

Centerline (Pitch): **2.54 mm [.1 in]**

Features

Product Type Features

| | |
|-----------------------------------|-----------------------|
| PCB Connector Assembly Type | PCB Mount Header |
| Connector System | Board-to-Board |
| Header Type | Breakaway |
| Sealable | No |
| Connector & Contact Terminates To | Printed Circuit Board |

Configuration Features

| | |
|----------------------------------|--------------|
| Number of Rows | 2 |
| Connector Contact Load Condition | Fully Loaded |
| PCB Mount Orientation | Right Angle |
| Number of Positions | 80 |

Electrical Characteristics

| | |
|-------------------|--------|
| Operating Voltage | 30 VAC |
|-------------------|--------|

Body Features

| | |
|-------------------|----------|
| Connector Profile | Standard |
|-------------------|----------|

Contact Features

| | |
|-------------------------------|-------------------|
| | 100 – 200 μ m |
| Contact Shape & Form | Square |
| Contact Underplating Material | Nickel |



| | |
|--|---|
| PCB Contact Termination Area Plating Material | Tin |
| Contact Base Material | Phosphor Bronze |
| Contact Mating Area Plating Material | Tin |
| Contact Mating Area Plating Material Thickness | 2.54 – 5.08 μm [100 – 200 μin] |
| Contact Type | Pin |
| Contact Current Rating (Max) | 3 A |

Termination Features

| | |
|---|-----------------------|
| Termination Post & Tail Length | 3.05 mm[.12 in] |
| Termination Method to Printed Circuit Board | Through Hole - Solder |

Mechanical Attachment

| | |
|--------------------------|------------------------|
| PCB Mount Retention Type | Retention Solder Tails |
| Mating Alignment | Without |
| PCB Mount Retention | With |
| PCB Mount Alignment | Without |
| Connector Mounting Type | Board Mount |

Housing Features

| | |
|--------------------|----------------|
| Centerline (Pitch) | 2.54 mm[.1 in] |
| Housing Color | Black |
| Housing Material | Thermoplastic |

Dimensions

| | |
|-----------------------------|------------------|
| Row-to-Row Spacing | 2.54 mm[.1 in] |
| PCB Thickness (Recommended) | 1.57 mm[.062 in] |

Usage Conditions

| | |
|-----------------------------|--|
| Housing Temperature Rating | Standard |
| Operating Temperature Range | -65 – 105 $^{\circ}\text{C}$ [-85 – 221 $^{\circ}\text{F}$] |

Operation/Application

| | |
|---------------------|--------|
| Circuit Application | Signal |
|---------------------|--------|

Industry Standards

| | |
|------------------------|-----------------------|
| Approved Standards | CSA LR7189, UL E28476 |
| UL Flammability Rating | UL 94V-0 |

Packaging Features

| | |
|--------------------|----|
| Packaging Quantity | 25 |
|--------------------|----|

Packaging Method

Tray

Other

Comment

Refer to the customer drawing to determine the number and location of the board retention tails. Other tail lengths are available, consult AMP Incorporated.

Product Compliance

[For compliance documentation, visit the product page on TE.com>](#)

EU RoHS Directive 2011/65/EU

Compliant

EU ELV Directive 2000/53/EC

Compliant

China RoHS 2 Directive MIIT Order No 32, 2016

No Restricted Materials Above Threshold

EU REACH Regulation (EC) No. 1907/2006

Current ECHA Candidate List: JUN 2020 (209)
Candidate List Declared Against: JAN 2020 (205)
Does not contain REACH SVHC

Halogen Content

Not Yet Reviewed for halogen content

Solder Process Capability

Wave solder capable to 265°C

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

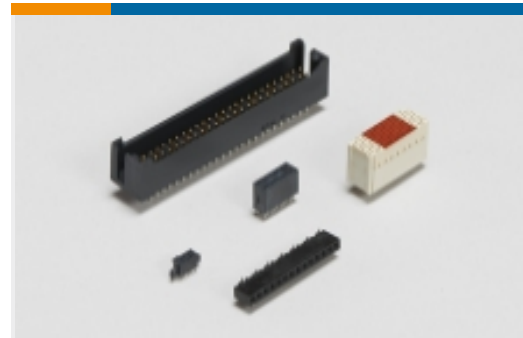
Compatible Parts



Also in the Series | AMPMODU Headers



Automotive Headers(10)



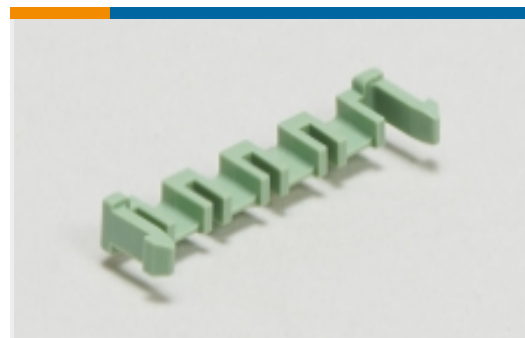
Board-to-Board Headers & Receptacles(6613)



PCB Connector Mounting(1)



PCB Connector Shrouds(1)



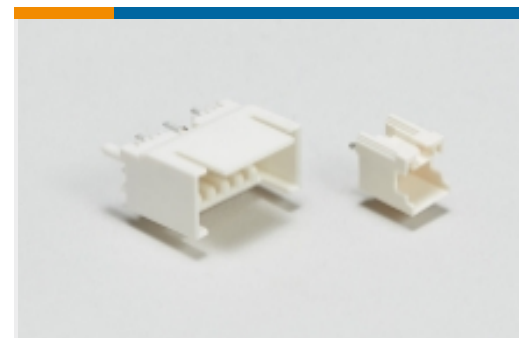
PCB Latches, Locks & Retainers(2)



Wire-to-Board Connector Assemblies & Housings(3)



Wire-to-Board Connector Contacts(52)



Wire-to-Board Headers & Receptacles (79)

Documents

Product Drawings

80 MODII HDR DRRR B/A W/HLDWN LF

English

CAD Files

3D PDF

3D

Customer View Model

[ENG_CVM_CVM_7-104355-0_L.2d_dxf.zip](#)

English

Customer View Model

[ENG_CVM_CVM_7-104355-0_L.3d_igs.zip](#)

English

Customer View Model

[ENG_CVM_CVM_7-104355-0_L.3d_stp.zip](#)

English

By downloading the CAD file I accept and agree to the [Terms and Conditions](#) of use.

Datasheets & Catalog Pages

AMPMODU Interconnection System

English

AMPMODU Interconnection System